



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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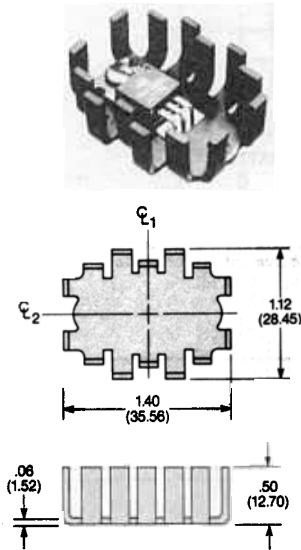
SECTION 2

HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

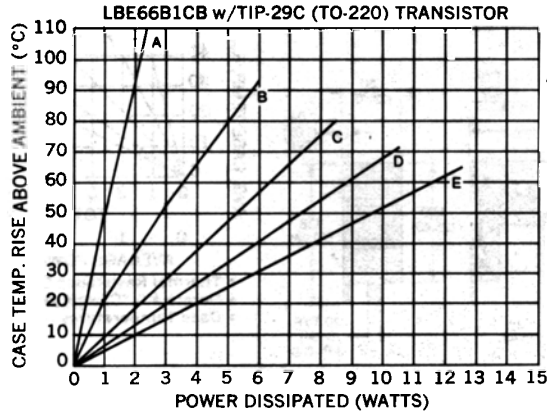
Board-mounted heat dissipators

- These compact, high-performance heat dissipators have exceptional volume/thermal efficiency ratios, making them especially effective where board space is limited and power levels are high.
- A wide range of hole patterns is available for single and multiple semiconductor mounting.
- Various finger heights in the LA, LB and UP Series optimize power dissipation, permit tailoring the heat dissipator to match vertical height requirements.

LB-B1 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

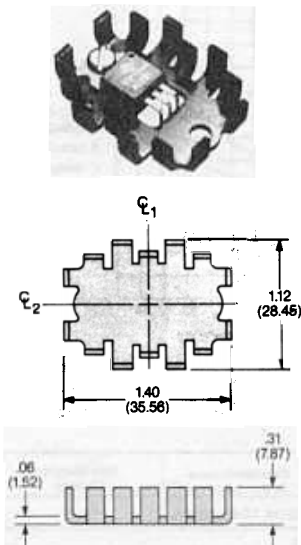
- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 0.4 °C/watt for unplated part in natural convection only.
- Derate 3.0 °C/watt for Insulube® part in natural convection only.

Ordering Information

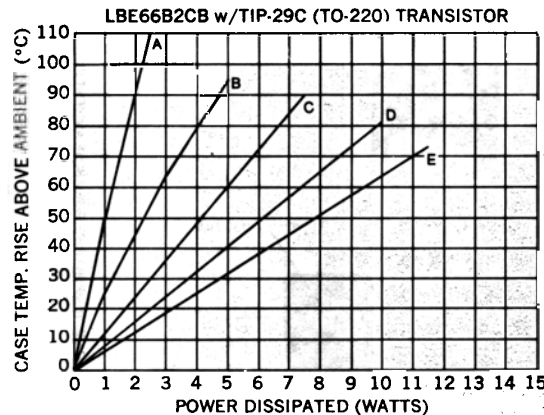
IERC PART NO.				Semiconductor Accommodated	Hole patt. ref. no. (see pg. 2-27)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Insulube® 448			
LBE66B1-76U LBE66B1U	LBE66B1-76CB LBE66B1CB	LBE66B2-76B LBE66B2B	LBE66B1-76 LBE66B1	Undrilled TO-126, TO-220	— 1	6.2 6.2

Note: See page iv for other finishes.

LB-B2 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 0.4 °C/watt for unplated part in natural convection only.
- Derate 3.0 °C/watt for Insulube® part in natural convection only.

Ordering Information

IERC PART NO.				Semiconductor Accommodated	Hole patt. ref. no. (see pg. 2-27)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Insulube® 448			
LBE66B2-76U LBE66B2U	LBE66B2-76CB LBE66B2CB	LBE66B2-76B LBE66B2B	LBE66B2-76 LBE66B2	Undrilled TO-126, TO-220	— 1	4.8 4.8

Note: See page iv for other finishes.